

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hideo MOCHIZUKI	09/26/2011
RECEIVING PARTY DATA	
Name:	Renesas Electronics Corporation
Street Address:	1753, Shimonumabe, Nakahara-ku
City:	Kawasaki-shi, Kanagawa
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13272856
CORRESPONDENCE DATA	
Fax Number:	(202)672-5399
Phone:	202-672-5300
Email:	rhale@foley.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	Foley & Lardner LLP
Address Line 1:	3000 K Street NW
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20007
ATTORNEY DOCKET NUMBER:	098211-0146
NAME OF SUBMITTER:	Effie Hale for George C. Beck
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PATENT
REEL: 027062 FRAME: 0964

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation,
a corporation organized under the laws of Japan,
located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

MEMORY INTERFACE CIRCUIT AND SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said Renesas Electronics Corporation,
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Hideo Mochizuki Hideo MOCHIZUKI

September 26, 2011

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